

SOT650-1

plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 3 mm x 3 mm x 0.85 mm

13 July 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON10
Package type industry code	HVSON10
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	8-2-2002
Manufacturer package code	SOT650

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	0.85	1	mm
A ₂	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	10	-	

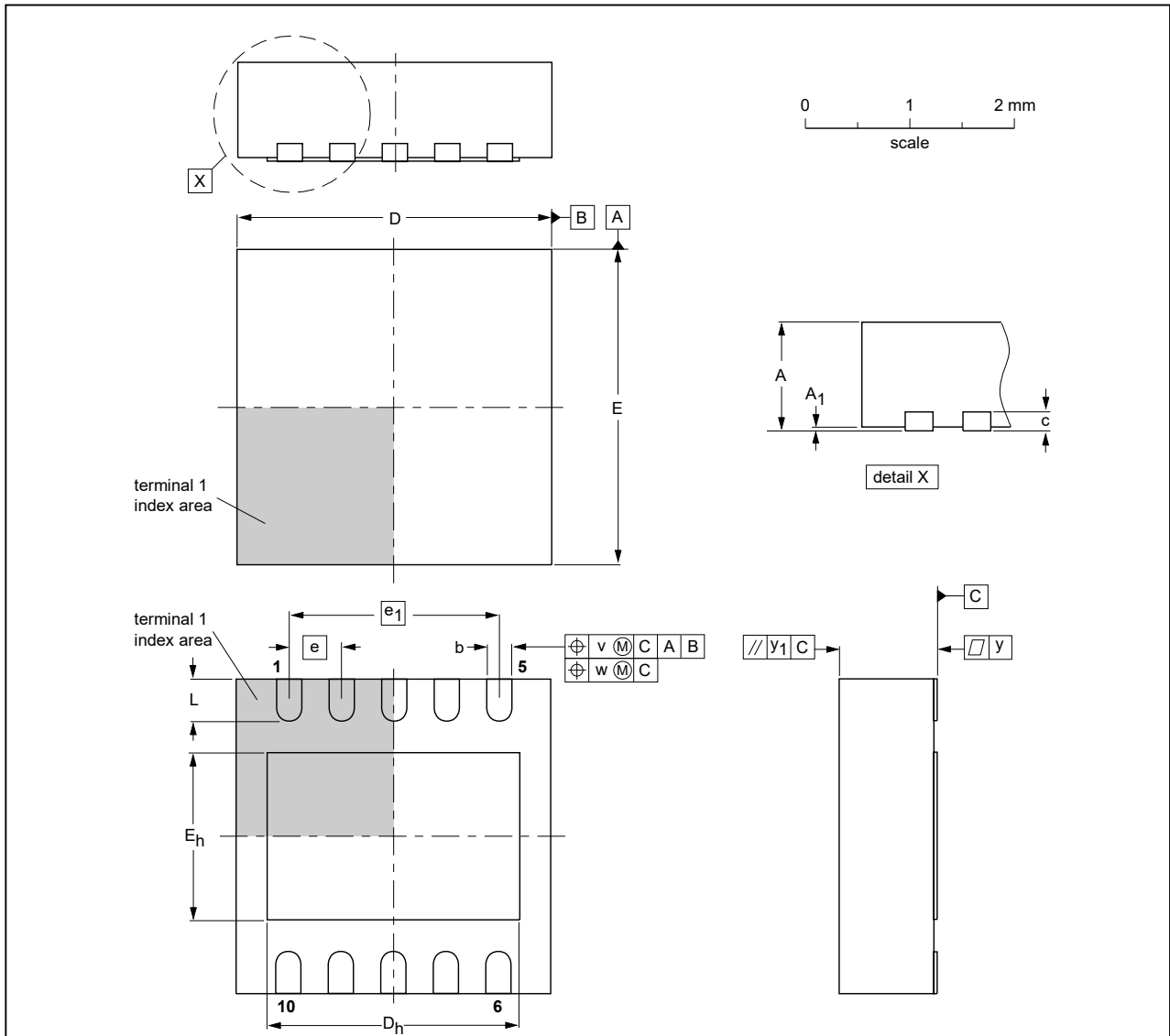


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2. Package outline

HVSON10: plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 3 x 3 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	2.55 2.15	3.1 2.9	1.75 1.45	0.5	2	0.55 0.30	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT650-1	---	MO-229	---			01-01-22- 02-02-08

Fig. 1. Package outline HVSON10 (SOT650-1)

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3. Soldering

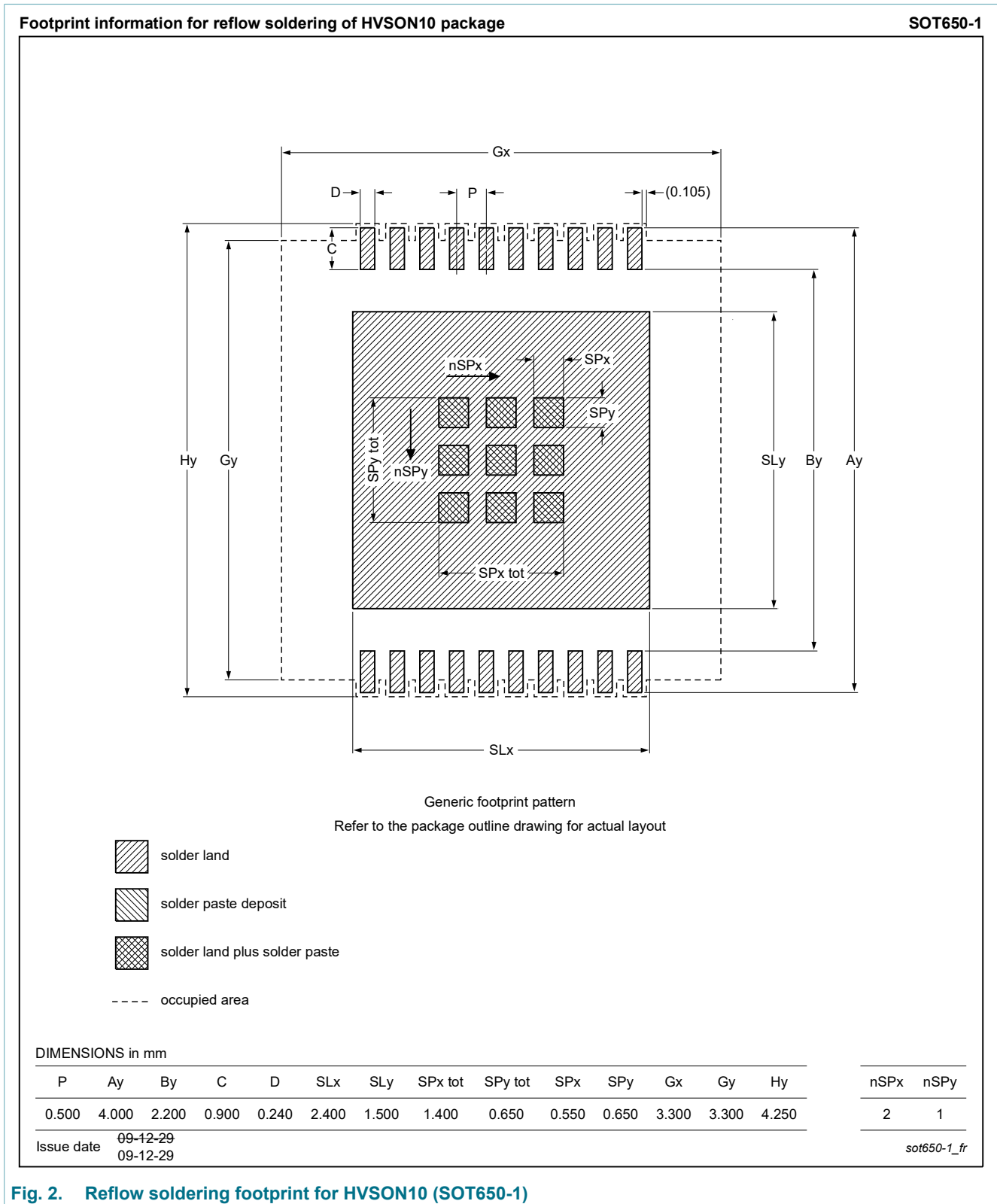


Fig. 2. Reflow soldering footprint for HVSON10 (SOT650-1)

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4. Legal information

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